

EAST Search History

EAST Search History (Prior Art)

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|-------|--|---|------------------|---------|------------------|
| S10 | 6 | ((HANNES) near2 (HORMANN)).INV. | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2009/05/06 19:07 |
| S20 | 73262 | method with ((printed with circuit with board) or (circuit with board) or pcb) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | OFF | 2009/05/12 13:38 |
| S21 | 27263 | S20 and (vias or via or trench or recess) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | OFF | 2009/05/12 13:39 |
| S22 | 15426 | S21 and (dielectric or insulat\$3) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2009/05/12 13:40 |
| S23 | 620 | S22 and (laser with ablation) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2009/05/12 13:40 |
| S29 | 1072 | laser with ((direct-write) or (direct write)) | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/12 17:30 |
| S30 | 4 | S29 with ((printed with circuit with board) or (circuit with board) or pcb) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | OFF | 2009/05/12 17:31 |
| S34 | 4073 | (circuit board) with coat\$3 with (dielectric or insulat\$3) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2009/05/12 18:45 |
| S35 | 1 | S34 with (pulse\$3 with laser) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2009/05/12 18:45 |
| S36 | 215 | S34 and laser with (ablat\$3 or remov \$3) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2009/05/12 18:47 |
| S38 | 91 | laser with ((direct-write) or (direct write)) with (pulse\$3 with laser) | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/05/12 18:50 |
| S47 | 73262 | method with ((printed with circuit with board) or (circuit with board) or pcb) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | OFF | 2009/05/13 11:10 |
| S49 | 50 | S47 and (horizontal with technique) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | OFF | 2009/05/13 11:11 |
| S60 | 73262 | method with ((printed with circuit with board) or (circuit with board) or pcb) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | OFF | 2009/05/13 11:30 |

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| S61 | 843 | S60 and (horizontal with (technique or method)) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | OFF | 2009/05/13 11:30 |
| S62 | 117 | S61 and (dip\$4) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | OFF | 2009/05/13 11:30 |
| S63 | 371 | (205/80).CCLS | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2009/05/15 09:32 |
| S67 | 3654 | (428/209).CCLS | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2009/05/15 09:35 |
| S60 | 247 | S67 and laser with (ablat\$3 or remov \$3) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2009/05/15 09:37 |
| S61 | 16 | S60 and (via or vias) and (trench or recess) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | OFF | 2009/05/15 09:37 |
| S62 | 3705 | (428/209).CCLS | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2009/11/02 09:44 |
| S63 | 252 | S62 and laser with (ablat\$3 or remov \$3) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2009/11/02 09:44 |
| S64 | 76462 | method with ((printed with circuit with board) or (circuit with board) or pcb) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | OFF | 2009/11/02 09:56 |
| S65 | 879 | S64 and (horizontal with (technique or method)) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | OFF | 2009/11/02 09:56 |
| S70 | 250429 | *428*/\$.ccls. | US-PGPUB; USPAT; USOCR | ADJ | ON | 2009/11/02 15:35 |
| S71 | 12638 | S70 AND S69 | USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2009/11/02 15:36 |
| S72 | 464 | S71 and (pcb or printed circuit board) | USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2009/11/02 15:37 |
| S73 | 252550 | *428*/\$.ccls. | US-PGPUB; USPAT; USOCR | ADJ | ON | 2010/01/11 18:25 |
| S74 | 4673 | S73 and (pcb or (print\$3 circuit board)) | US-PGPUB; USPAT; USOCR | ADJ | ON | 2010/01/11 18:27 |
| S75 | 2838 | S74 and @pd< "20040129" | US-PGPUB; USPAT; USOCR | ADJ | ON | 2010/01/11 18:28 |
| S76 | 7 | S75 and (via or vias) and (trench or recess) and trace | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | OFF | 2010/01/11 18:29 |

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| S79 | 6352 | (29/630,631,632,652).CCL.S. | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2010/01/21 16:52 |
| S80 | 47 | S79 and (PCB or (print\$3 circuit board)) and traces and dielectric and (laser ablation) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2010/01/21 16:53 |
| S83 | 91 | S79 and (PCB or (print\$3 circuit board)) and ((copper or metal) adj layer) and dielectric and (laser ablation) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2010/01/21 17:51 |
| S85 | 70 | ((MAFK) near2 (MOCORMACK)).INV. | US-PGPUB; USPAT; USOCR | ADJ | ON | 2010/01/21 17:59 |
| S86 | 31 | (high density interconnection) and (PCB or (print\$3 circuit board)) and ((copper or metal) adj layer) and dielectric and (laser ablation) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2010/01/21 18:29 |
| S87 | 49 | (high density interconnection) and ((copper or metal) adj layer) and dielectric and (laser ablation) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2010/01/21 18:48 |
| S89 | 6586 | (29/630,631,632,652).CCL.S. | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2010/06/18 18:53 |
| S90 | 97 | S89 and (PCB or (print\$3 circuit board)) and ((copper or metal) adj layer) and dielectric and (laser ablation) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2010/06/18 18:53 |
| S96 | 35 | ((REINHARD) near2 (SCHNEIDER)).INV. | US-PGPUB; USPAT; USOCR | ADJ | ON | 2010/06/18 20:04 |
| S97 | 30 | ((DAVID) near2 (BARON)).INV. | US-PGPUB; USPAT; USOCR | ADJ | ON | 2010/06/18 20:06 |
| S98 | 3651 | (29/646).CCL.S. | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2010/06/18 20:38 |
| S103 | 4845 | (257/40).CCL.S. | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2010/06/19 10:15 |
| S104 | 259 | S103 and ((printed with circuit with board) or (circuit with board) or pcb) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | OFF | 2010/06/19 10:16 |
| S105 | 3651 | (29/646).CCL.S. | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2010/06/19 10:52 |
| S106 | 1976 | S105 and ((printed with circuit with board) or (circuit with board) or pcb) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | OFF | 2010/06/19 10:52 |
| S107 | 323 | S106 and (laser with (ablat\$3 or remov \$3)) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2010/06/19 10:53 |
| S108 | 208 | S106 and (laser with (ablat\$3 or remov \$3)) and @<2005" | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2010/06/19 10:53 |

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| SI11 | 14 | "29"/\$.cds. and (vias with V-shape) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2010/06/19 14:34 |
| SI12 | 8586 | (29/830,831,832,852).CCL.S | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2010/06/19 14:35 |
| SI14 | 3 | "428"/\$.cds. and (vias with V-shape) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2010/06/19 14:37 |
| SI15 | 3 | "428"/\$.cds. and ((vias or trench or trace) with V-shape) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2010/06/19 14:37 |
| SI16 | 3651 | (29/846).CCL.S | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2010/06/19 14:38 |
| SI18 | 3 | SI16 and ((vias or trench or trace) with V near shape) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2010/06/19 14:38 |
| SI19 | 65 | ((printed with circuit with board) or (circuit with board) or pcb) and ((vias or trench or trace) with V near shape) | US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB | ADJ | ON | 2010/06/19 14:49 |

6/19/2010 4:45:18 PM

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